Zener Diode

Unit: mm

0.7

3. Cathode-2

### DZ4J051K0R

2. 0

(0. 65)(0. 65)

1. Anode-1

# **Panasonic**

## **DZ4J051K0R**

### Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

#### ■ Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol:CJ
- Basic Part Number : Dual DZ2J051 (Parallel)
- Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

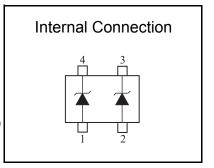
#### 4. Cathode-1 2. Anode-2 Panasonic SMini4-F3-B SC-113BB **JEITA** Code

## ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	200	mW
Electrostatic discharge *2	ESD	±15	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm) Solder in (0.8 mm x 0.8 mm)

<sup>\*2:</sup> Test method:IEC61000\_4\_2(C = 150 pF,R = 330  $\Omega$ , Contact discharge:10 times)



#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	4.85		5.36	V
Zener operating resistance	RZ	IZ = 5 mA			60	Ω
Zener rise operating resistance	RZK	IZ = 1 mA			500	Ω
Reverse current	IR	VR = 2 V			1.0	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		0.7		mV/°C

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. Absolute frequency of input and output is 5 MHz.
  - 3. \*1: The temperature must be controlled 25 °C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25 °C)
    - \*2: VZ guaranted 20 ms after current flow.
    - \*3: Tj = 25 °C to 150 °C

Established: 2009-12-11

Revised

: 2013-10-04

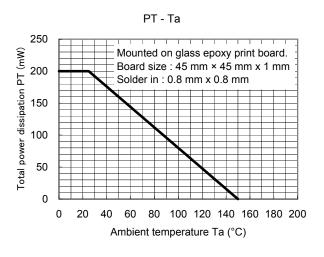
Page 1 of 4

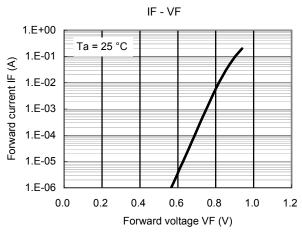
**Panasonic** 

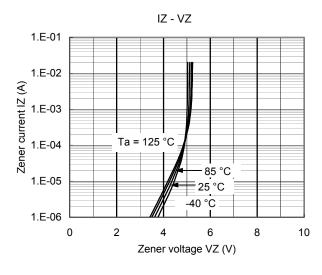
Zener Diode

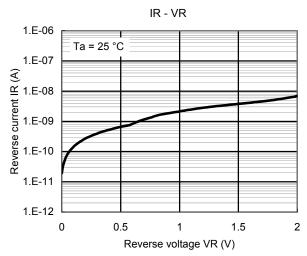
### **DZ4J051K0R**

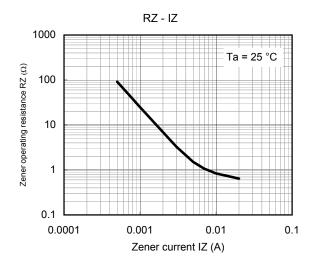
## Technical Data (reference)

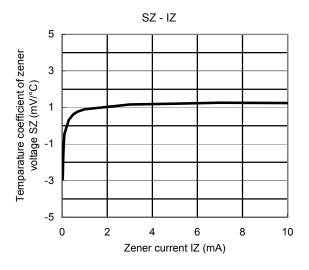










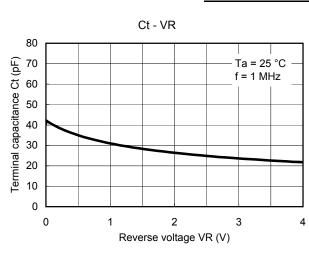


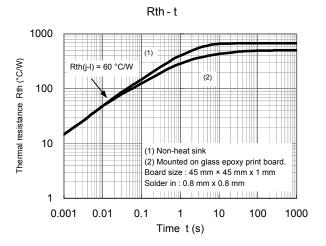
Established: 2009-12-11 Revised: 2013-10-04 **Panasonic** 

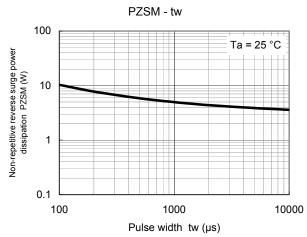
Zener Diode

## DZ4J051K0R

# Technical Data (reference)







Established: 2009-12-11 Revised: 2013-10-04

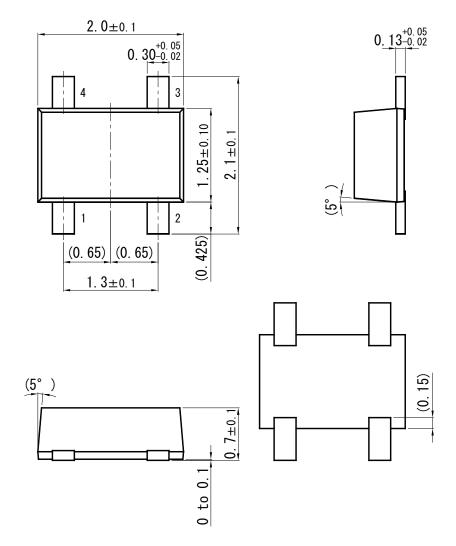
Zener Diode

# DZ4J051K0R

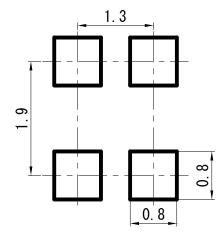
# SMini4-F3-B

**Panasonic** 

Unit: mm



### ■ Land Pattern (Reference) (Unit: mm)



Established: 2009-12-11 Revised: 2013-10-04

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